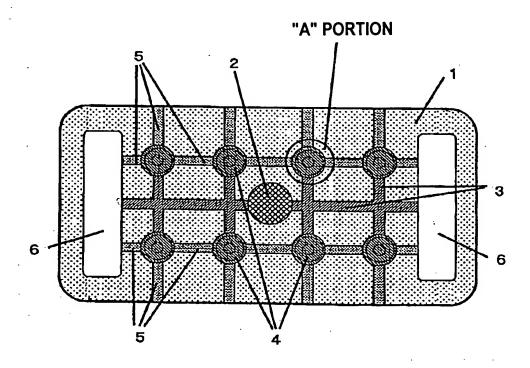
Inventor(s) Appl. N . Title

KURODA, Hirofumi
To Be Assigned
Epoxy Resin Composition and Semiconductor Device
Using Thereof
Concurrent Herewith
033036.001 Page: 1 of 3

Filing Date : Atty. Dkt. No. :

1/3

Fig.1



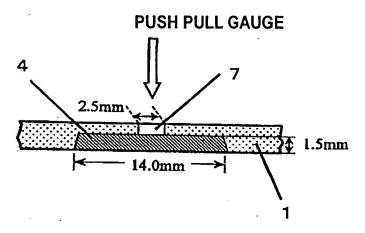
Inventor(s) Appl. No. Title KURODA, Hirofumi To Be Assigned

Epoxy Resin Composition and Semiconductor Device
Using Thereof
Concurrent Herewith
033036.001 Page: 2 of 3

Filing Date : Atty. Dkt. No. :

2/3

Fig.2



Inventor(s) Appl. No. Title

KURODA, Hirofumi
To Be Assigned
Epoxy Resin Composition and S miconductor Device
Using Thereof
C ncurrent Herewith
033036.001 Page: 3 f 3

Filing Date : Atty. Dkt. No. :

3/3

Fig.3

